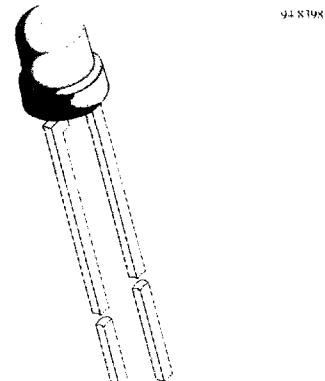


GaAlAs Infrared Emitting Diodes in ø 3 mm (T-1) Package

Description

The TSHA44..series are high efficiency infrared emitting diodes in GaAlAs on GaAlAs technology, molded in a clear, untinted plastic package.

In comparison with the standard GaAs on GaAs technology these high intensity emitters feature about 50 % radiant power improvement.



Features

- Extra high radiant power
- High radiant intensity for long transmission distance
- Suitable for high pulse current operation
- Standard T-1(ø 3 mm) package for low space application
- Angle of half intensity $\phi = \pm 20^\circ$
- Peak wavelength $\lambda_p = 875 \text{ nm}$
- High reliability
- Good spectral matching to Si photodetectors

Applications

Infrared remote control and free air transmission systems with high power requirements in combination with PIN photodiodes or phototransistors.

Because of the very low radiance absorption in glass at the wavelength of 875 nm, this emitter series is also suitable for systems with panes in the transmission range between emitter and detector.

Absolute Maximum Ratings

$T_{amb} = 25^\circ\text{C}$

Parameter	Test Conditions	Symbol	Value	Unit
Reverse Voltage		V_R	5	V
Forward Current		I_F	100	mA
Peak Forward Current	$t_p/T=0.5, t_p=100 \mu\text{s}$	I_{FPM}	200	mA
Surge Forward Current	$t_p=100 \mu\text{s}$	I_{FSM}	2	A
Power Dissipation		P_V	180	mW
Junction Temperature		T_j	100	°C
Operating Temperature Range		T_{amb}	-55...+100	°C
Storage Temperature Range		T_{stg}	-55...+100	°C
Soldering Temperature	$t \leq 5\text{sec}, 2 \text{ mm from case}$	T_{sd}	260	°C
Thermal Resistance Junction/Ambient		R_{thJA}	450	K/W

TSWA440.

TEMIC
Semiconductors

Basic Characteristics

T_{amb} = 25 °C

Parameter	Test Conditions	Symbol	Min	Typ	Max	Unit
Forward Voltage	I _F = 100 mA, t _p = 20 ms	V _F		1.5	1.8	V
	I _F = 1.5 A, t _p = 100 µs	V _F		3.2	4.9	V
Temp. Coefficient of V _F	I _F = 100 mA	TK _{VF}		-1.6		mV/K
Reverse Current	V _R = 5 V	I _R			100	µA
Junction Capacitance	V _R = 0 V, f = 1 MHz, E = 0	C _J		20		pF
Temp. Coefficient of φ _e	I _F = 100 mA	TK _{φe}		-0.7		%/K
Angle of Half Intensity		φ		±20		deg
Peak Wavelength	I _F = 100 mA	λ _p		875		nm
Spectral Bandwidth	I _F = 100 mA	Δλ		80		nm
Temp. Coefficient of λ _p	I _F = 100 mA	TK _{λp}		0.2		nm/K
Rise Time	I _F = 100 mA	t _r		600		ns
	I _F = 1.5 A	t _r		300		ns
Fall Time	I _F = 100 mA	t _f		600		ns
	I _F = 1.5 A	t _f		300		ns

Type Dedicated Characteristics

T_{amb} = 25 °C

Parameter	Test Conditions	Type	Symbol	Min	Typ	Max	Unit
Radiant Intensity	I _F =100mA, t _p =20ms	TSHA4400	I _e	12	20		mW/sr
		TSHA4401	I _e	16	30		mW/sr
	I _F =1.5A, t _p =100µs	TSHA4400	I _e	140	240		mW/sr
		TSHA4401	I _e	190	360		mW/sr
Radiant Power	I _F =100mA, t _p =20ms	TSHA4400	Φ _e		20		mW
		TSHA4401	Φ _e		24		mW

Typical Characteristics ($T_{amb} = 25^\circ\text{C}$ unless otherwise specified)

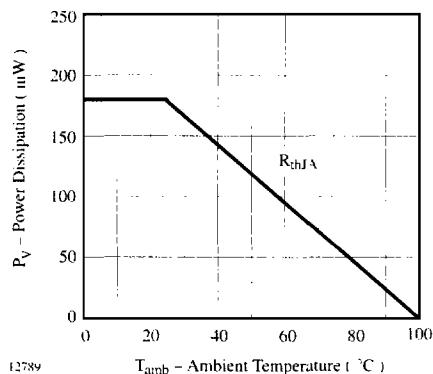


Figure 1. Power Dissipation vs. Ambient Temperature

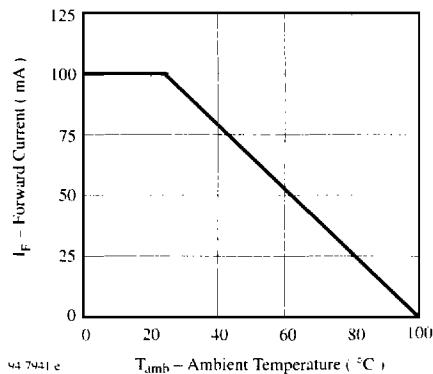


Figure 2. Forward Current vs. Ambient Temperature

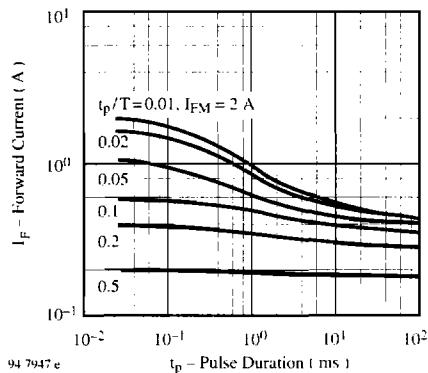


Figure 3. Pulse Forward Current vs. Pulse Duration

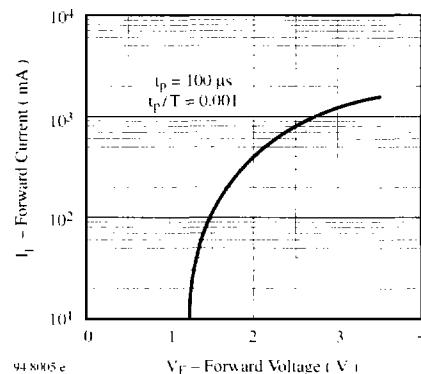


Figure 4. Forward Current vs. Forward Voltage

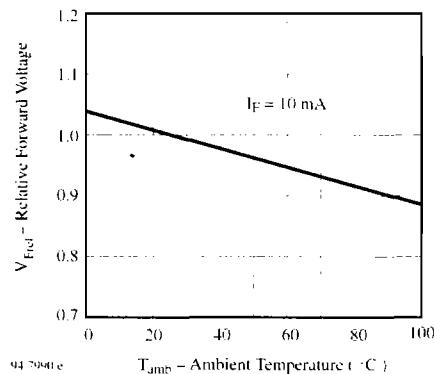


Figure 5. Relative Forward Voltage vs. Ambient Temperature

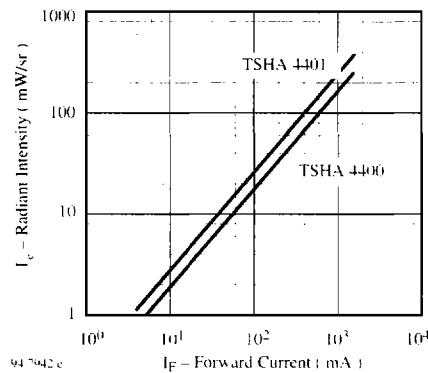


Figure 6. Radiant Intensity vs. Forward Current

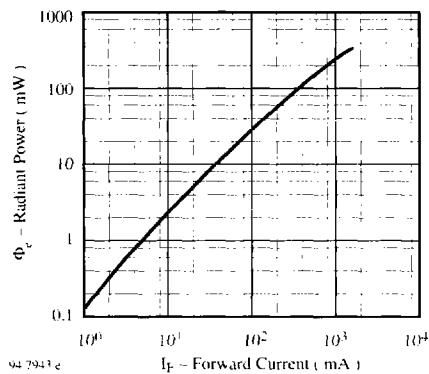


Figure 7. Radiant Power vs. Forward Current

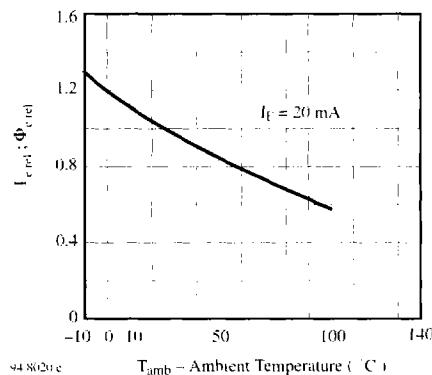


Figure 8. Rel. Radiant Intensity/Power vs. Ambient Temperature

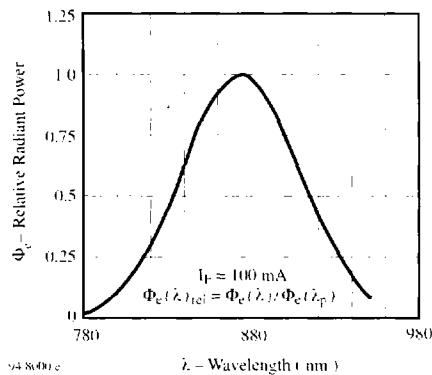


Figure 9. Relative Radiant Power vs. Wavelength

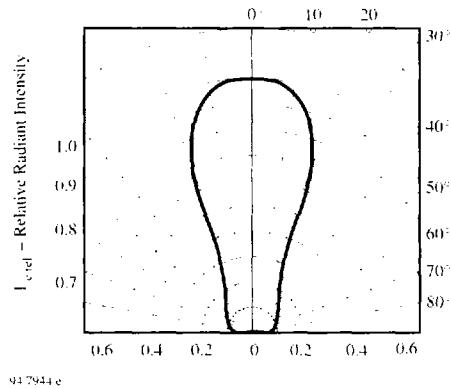
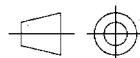
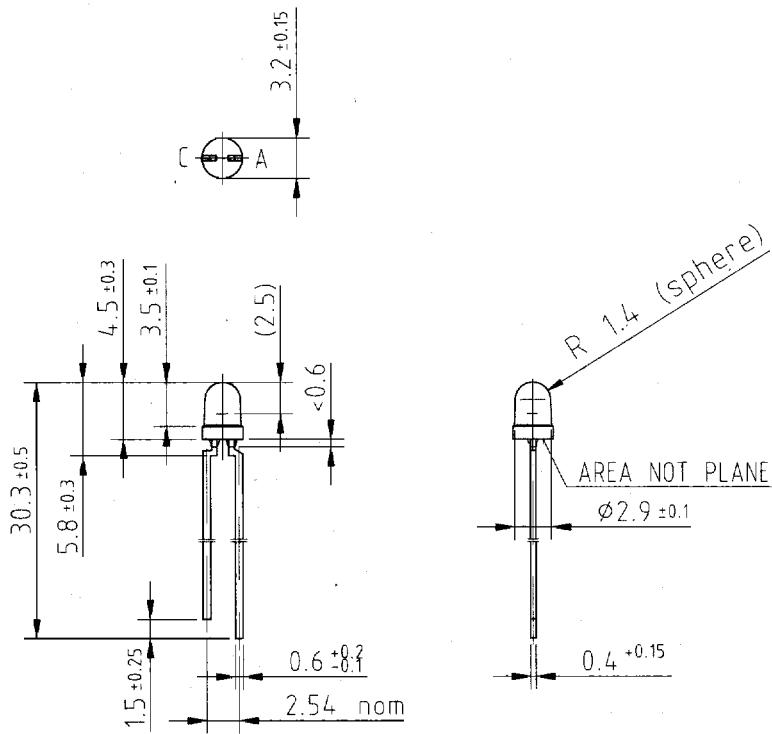


Figure 10. Relative Radiant Intensity vs. Angular Displacement

Dimensions in mm



technical drawings
according to DIN
specifications